

Docket No.: 50088-056

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Eiji HAYASHI

Serial No.:

Filed: March 19, 2001

For: FLIP CHIP BONDING METHOD

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Group Art Unit:

Examiner:

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
Washington, DC 20231

Dear Sir:

In accordance with the provisions of 37 C.F.R. 1.56, 1.97 and 1.98, the attention of the Patent and Trademark Office is hereby directed to the documents listed on the attached form PTO-1449. It is respectfully requested that the documents be expressly considered during the prosecution of this application, and that the documents be made of record therein and appear among the "References Cited" on any patent to issue therefrom.

This Information Disclosure Statement is being filed within three months of the U.S. filing date OR before the mailing date of a first Office Action on the merits. No certification or fee is required.

In JP-A-11-284028 an ultrasonic wave is applied at time of connecting a flip chip in perpendicular two directions or three directions mutually shifted by 120°. In JP-A-8-139138 an ultrasonic wave is applied at time of connecting a flip chip in perpendicular two directions or three

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directions mutually shifted by 120°. In JP-A-11-97493 an ultrasonic wave is applied at time of connecting a flip chip in perpendicular two directions or three directions mutually shifted by 120°.

Respectfully submitted,

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